

# **TPF EXPO**

## **Current Development Status of the ACTDP Program at NGST**

**10/16/03**

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## Program Scope

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- The contractor shall
  - design, fabricate, assemble test and deliver
    - an ACTDP cryocooler thermal mechanical unit engineering model (EM)
    - brass board electronics (BE),
    - and associated test equipment and documentation.

## Program Objectives

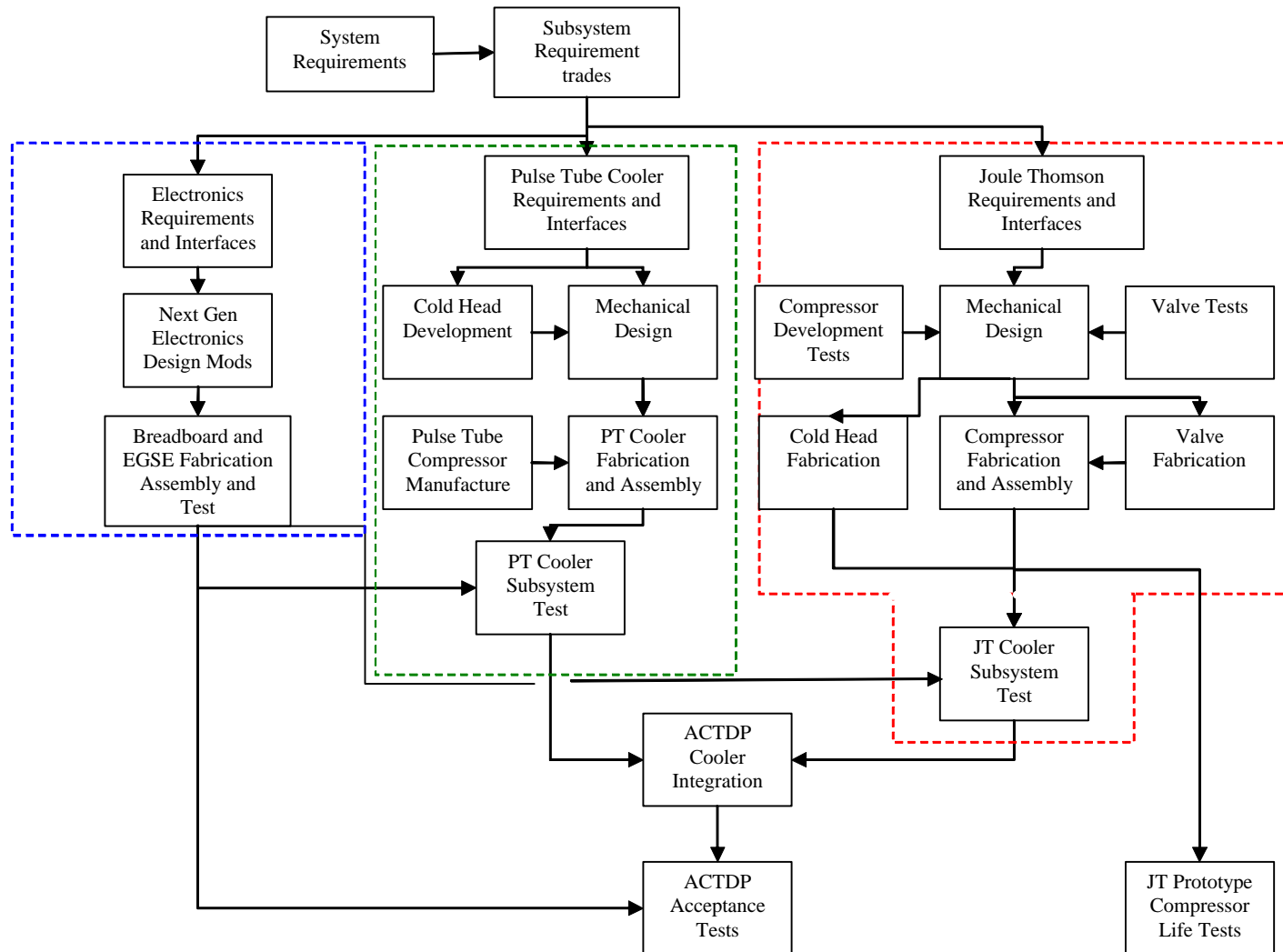
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- The objective of this program is to
  - Develop an efficient 2 stage EM mechanical cooler providing cooling at 6K and 18K
  - The mechanical cooler shall be form, fit and function identical to a flight cooler
  - The cooler shall be designed to the requirements of the ACTDP Cryocooler Specification (TPF, ConX, JWST)
  - The cooler shall be designed with modular components
  - The cooler shall incorporate simple mechanical, thermal and electrical interfaces

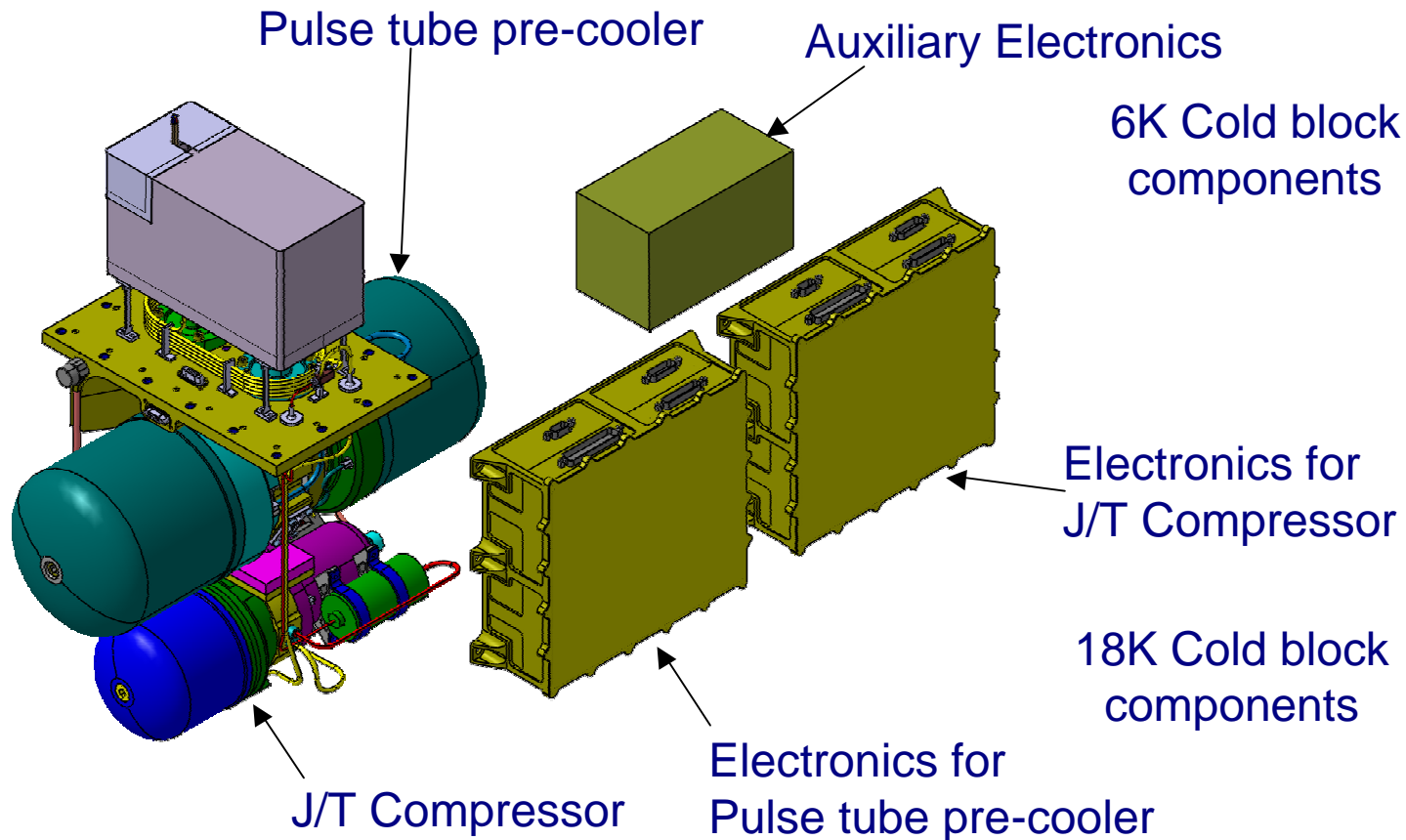
# Program Milestones

Contract Deliverable Status			
1	Progress Report		Monthly
2	Kick-Off Meeting	NGST	5/21/03
3	Delta Preliminary Design Review	NGST	8/27/03
4	TIM #1/ Progress Briefing	JPL	10/16/03
5	TIM #2	NGST	1/20/04
6	Critical Design Review	JPL	5/18/04
7	TIM #3	NGST	7/20/04
8	TIM #4/ Progress Briefing	JPL	10/19/04
9	Environmental Test Review	NGST	12/21/04
10	TIM #5 (Pre-JWST NAR)	NGST	4/19/05
11	TIM #6	NGST	7/19/05
12	System Test Report (Draft)		7/19/05
13	Acceptance Data Package (Draft)		7/19/05
14	TIM #7/ Progress Briefing	JPL	10/18/05
15	Pre-Ship Review	NGST	12/20/05
16	System Test Report (Final)		12/20/05
17	Acceptance Data Package (Final)		12/20/05
18	Development Plan, Flight Cryocooler		12/20/05
19	Delivery: EM TMU, BE, spt & test eqpt.	JPL	12/20/05

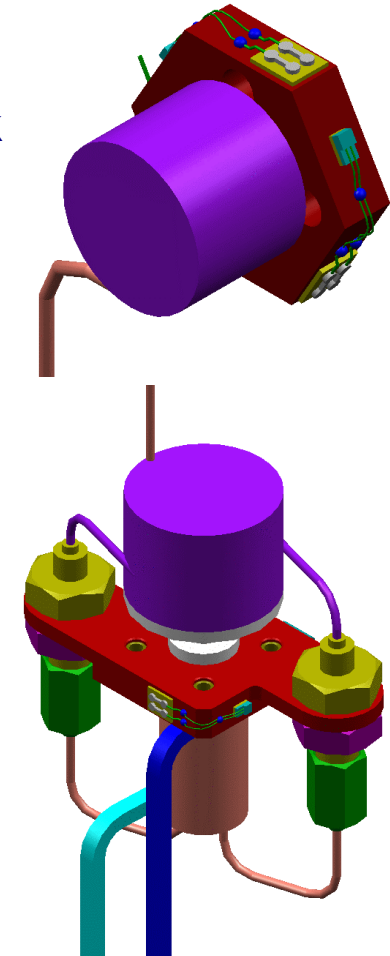
# Project Flow



# ACTDP Cooler Components



**Bus-mounted  
Cryocooler  
components**

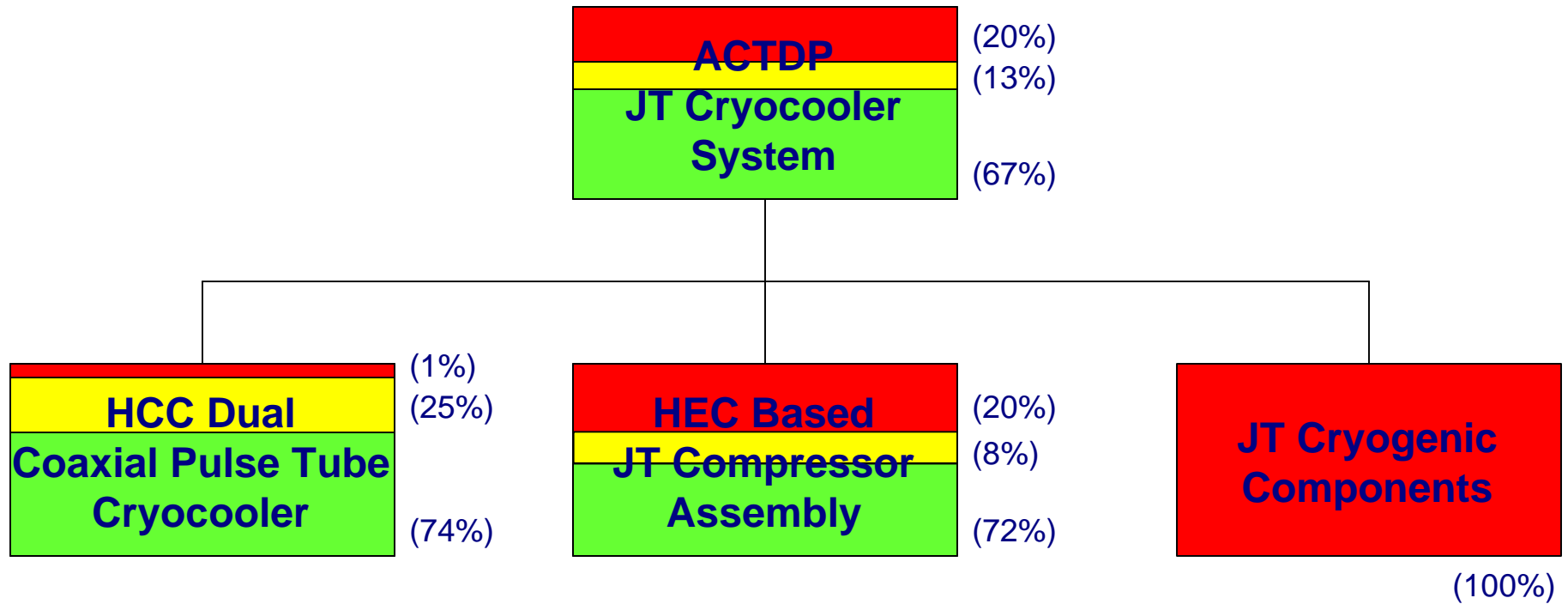


**Instrument  
mounted  
components**

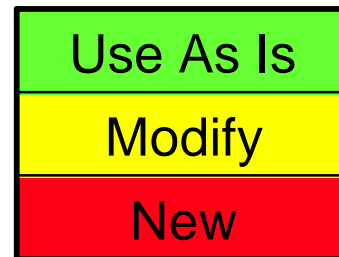
**Not to scale**

# Mechanical Design Maturity - Summary

Top-Level Drawing Tree:



Color Key:



# Program Status

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- Project
  - Delta PDR completed 8/27/03
- System Engineering
  - Integrated system power model complete
  - Trades performed on:
    - Precooler temperature
    - JT mass flow
    - Complexity
    - Power on 85K precooler stage
    - Recuperator form
    - Packaging
- Pulse Tube pre-cooler
  - Extensive cold head modeling performed to direct lab development activities
  - 3<sup>rd</sup> stage cold head testing in process
  - Integrated two-stage 35K/17K cold head testing started



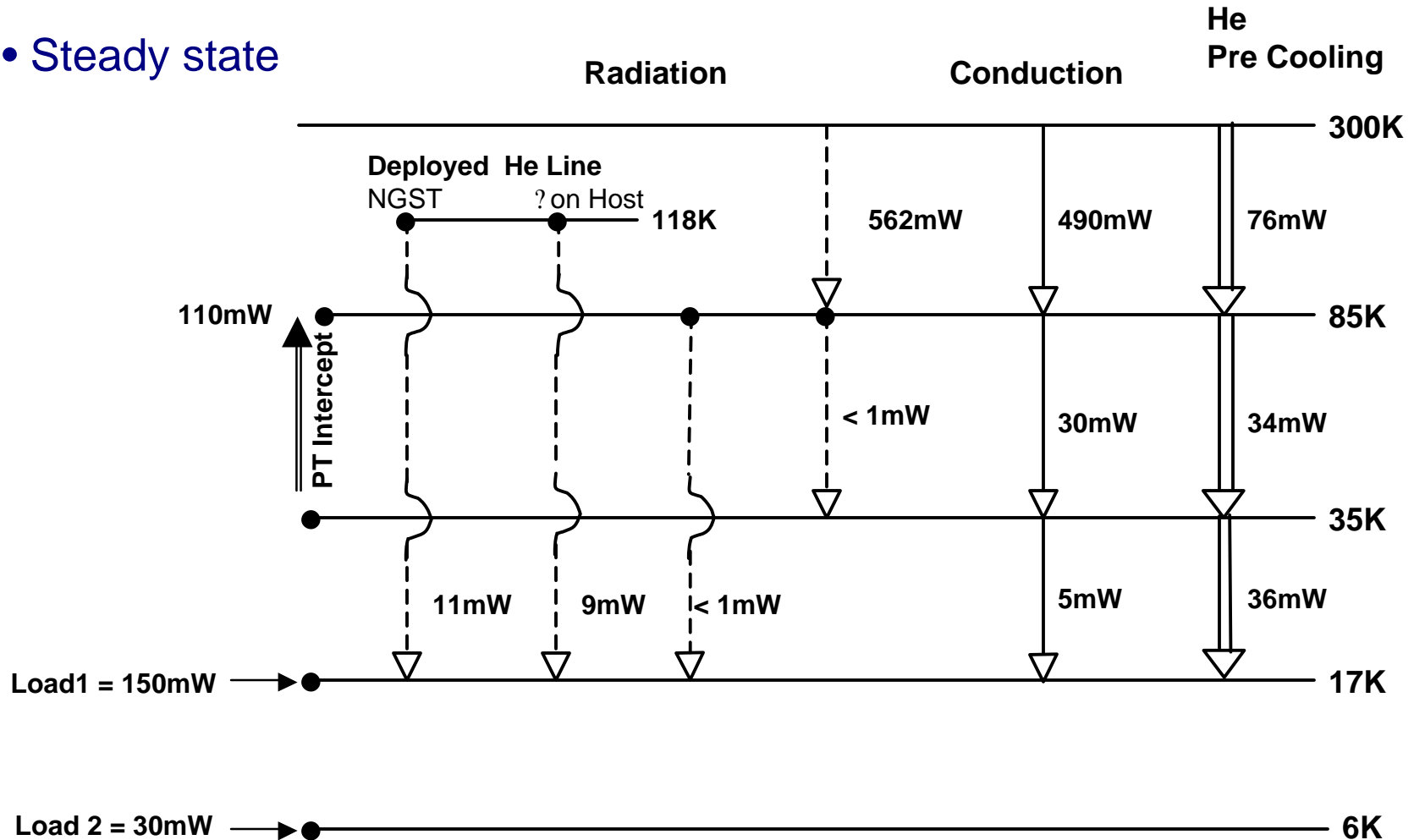
## Program Status (cont)

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- JT cooler
  - Refined preliminary baseline design for recuperator
  - Baseline preliminary precooler HEXs defined
  - Completed compressor testing
- Mechanical Design
  - Baseline preliminary design for majority of pulse tube pre-cooler cold heads, recuperator and HEXs defined
  - System mass budget with growth allocation established
- Electrical Design
  - Deferred to 2005
    - Electronics is essentially build to print therefore very low risk

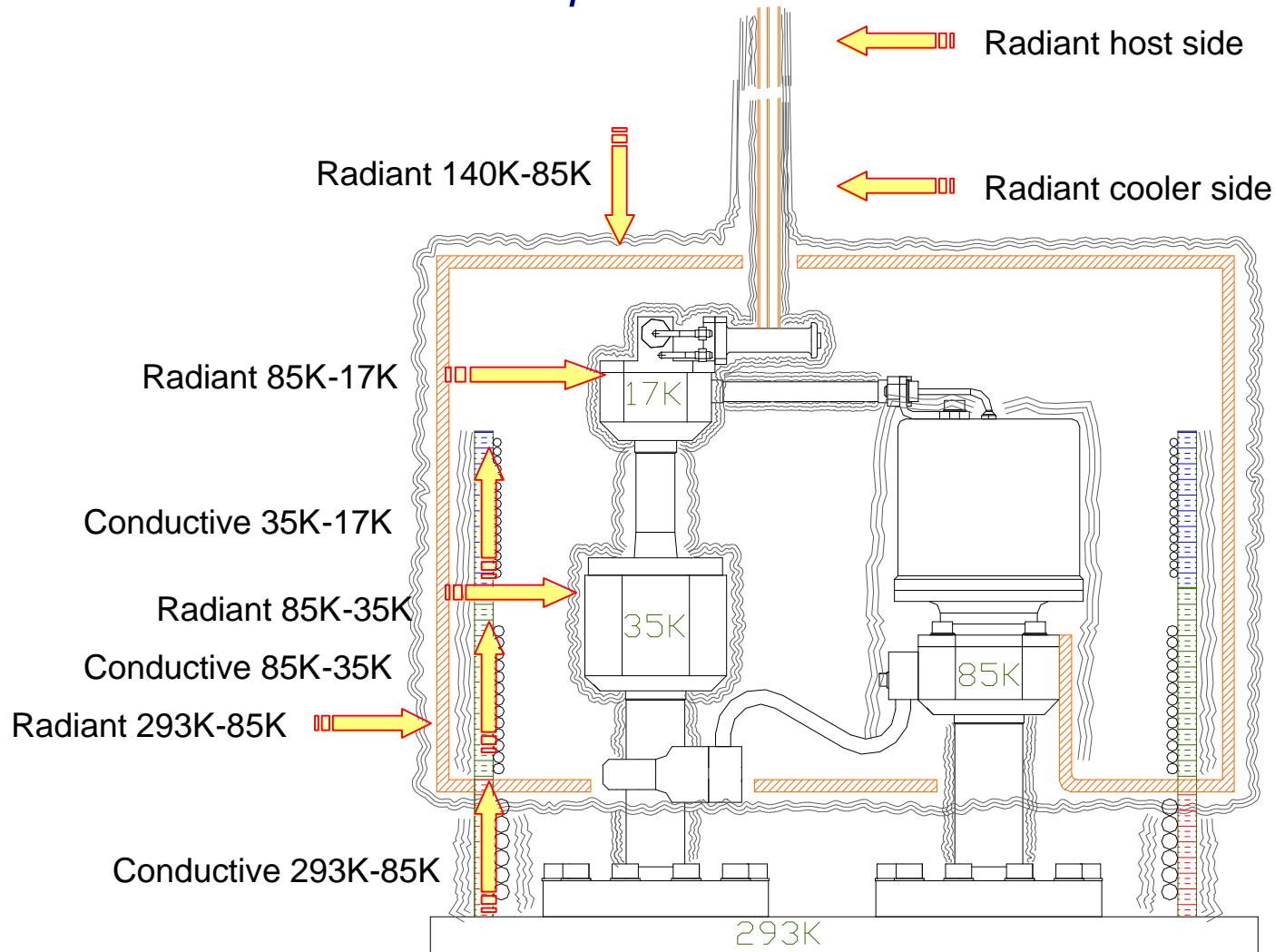
# Thermal map of ACTDP Cooler

- Steady state



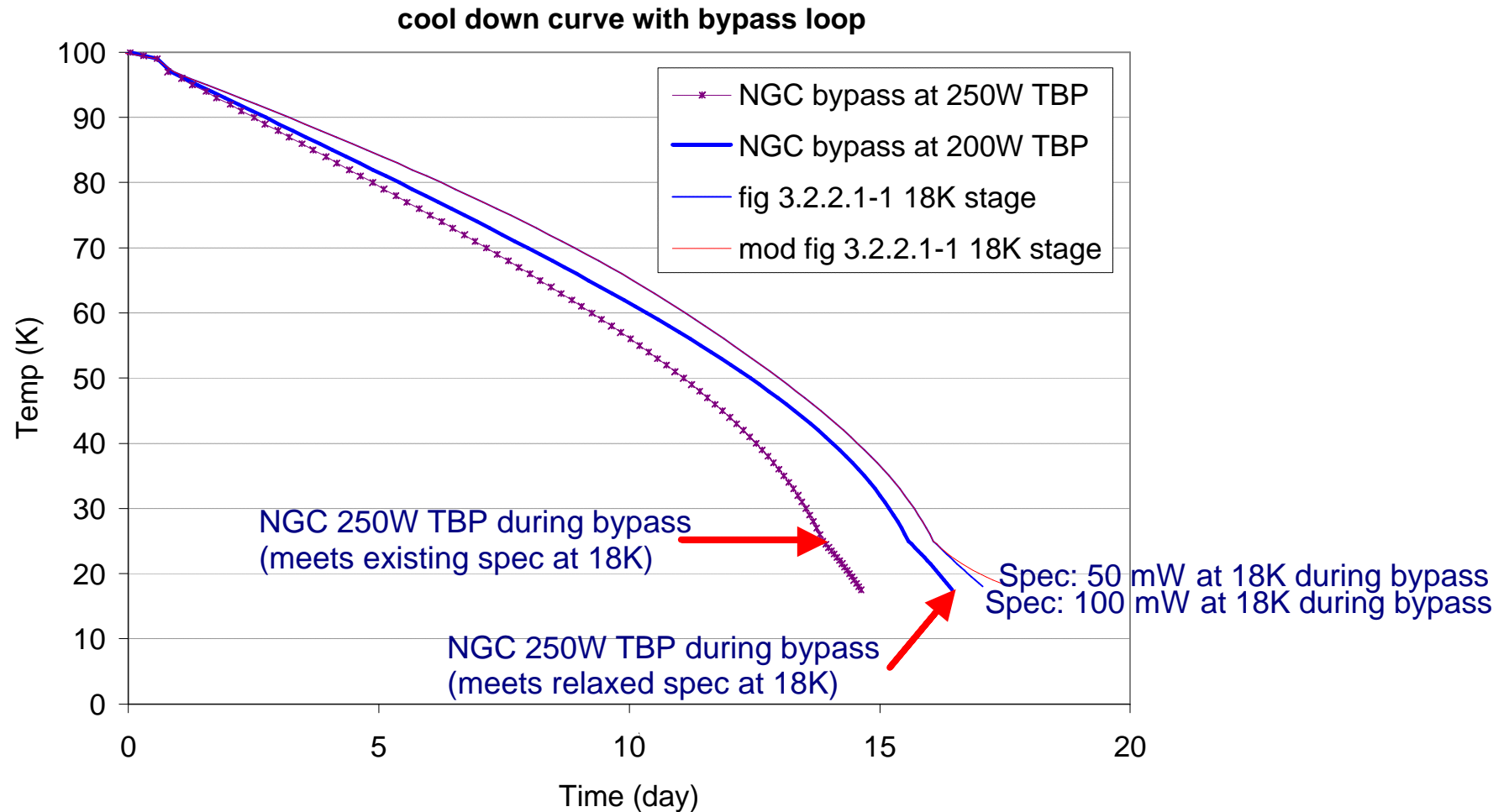
# Parasitic Loads on PT Coldheads

*Thermal model accounts for all parasitic heat leaks*

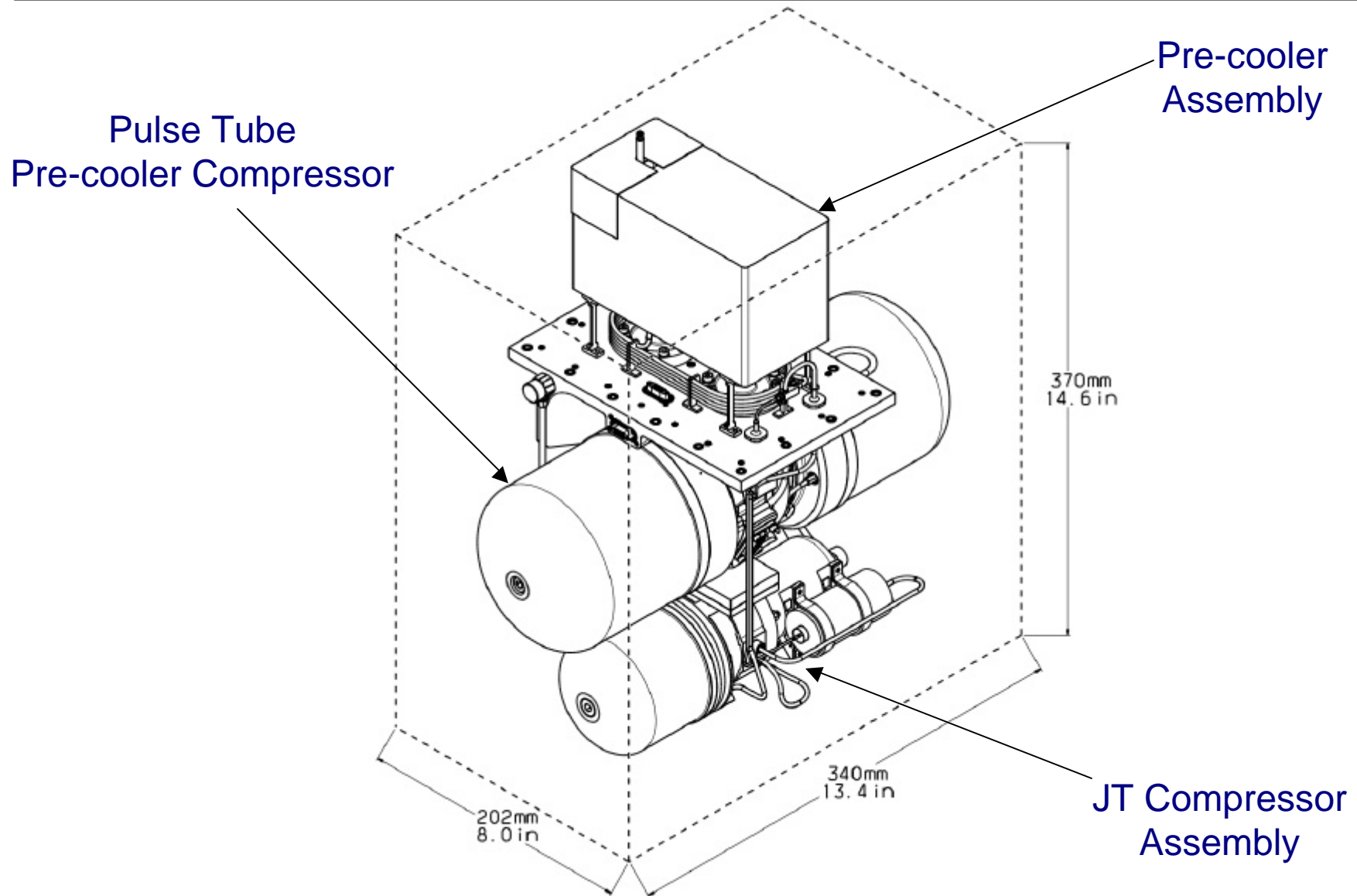


# JT Loop – Cool down to 18K

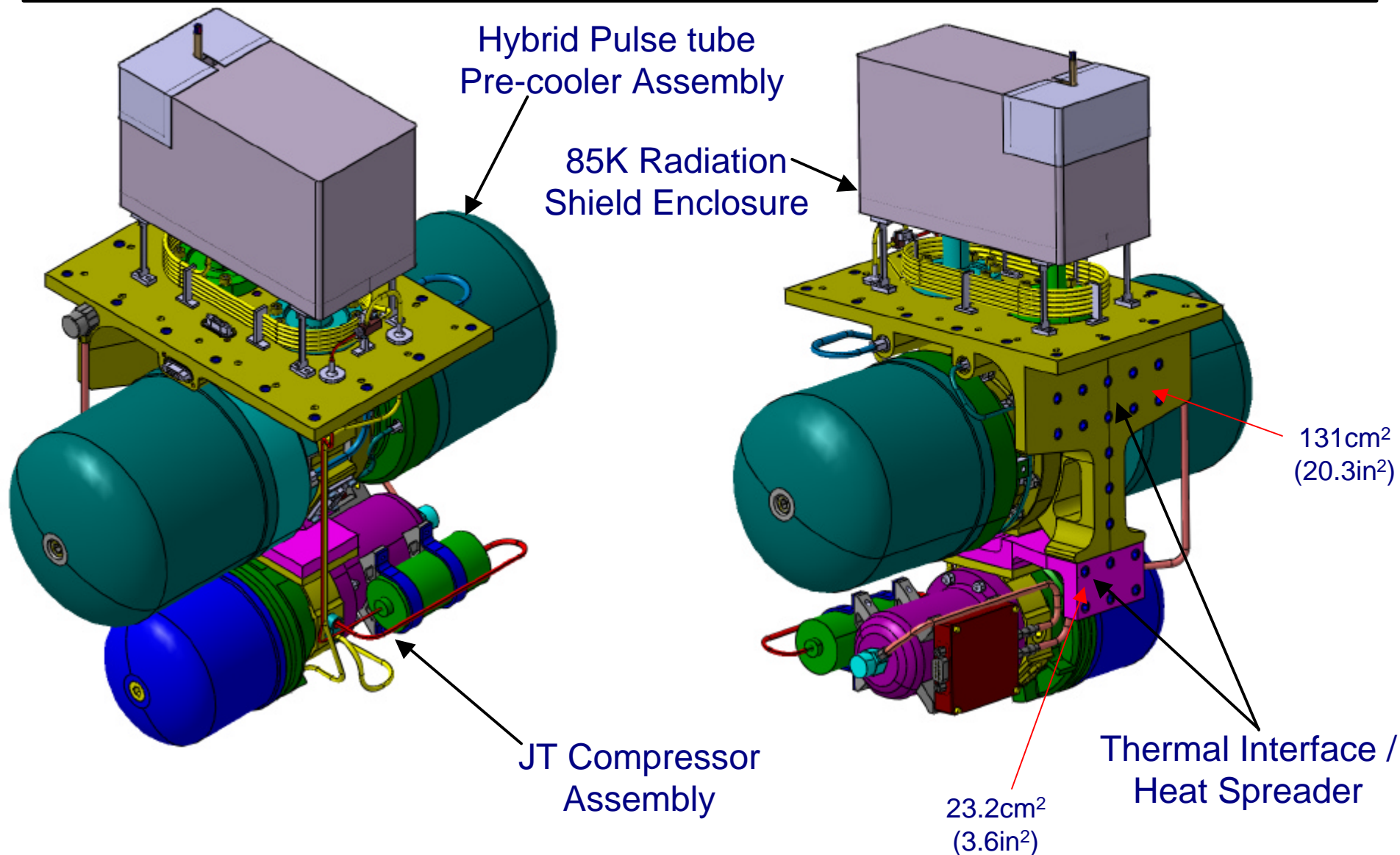
Margin against the cooldown time corresponding to the spec



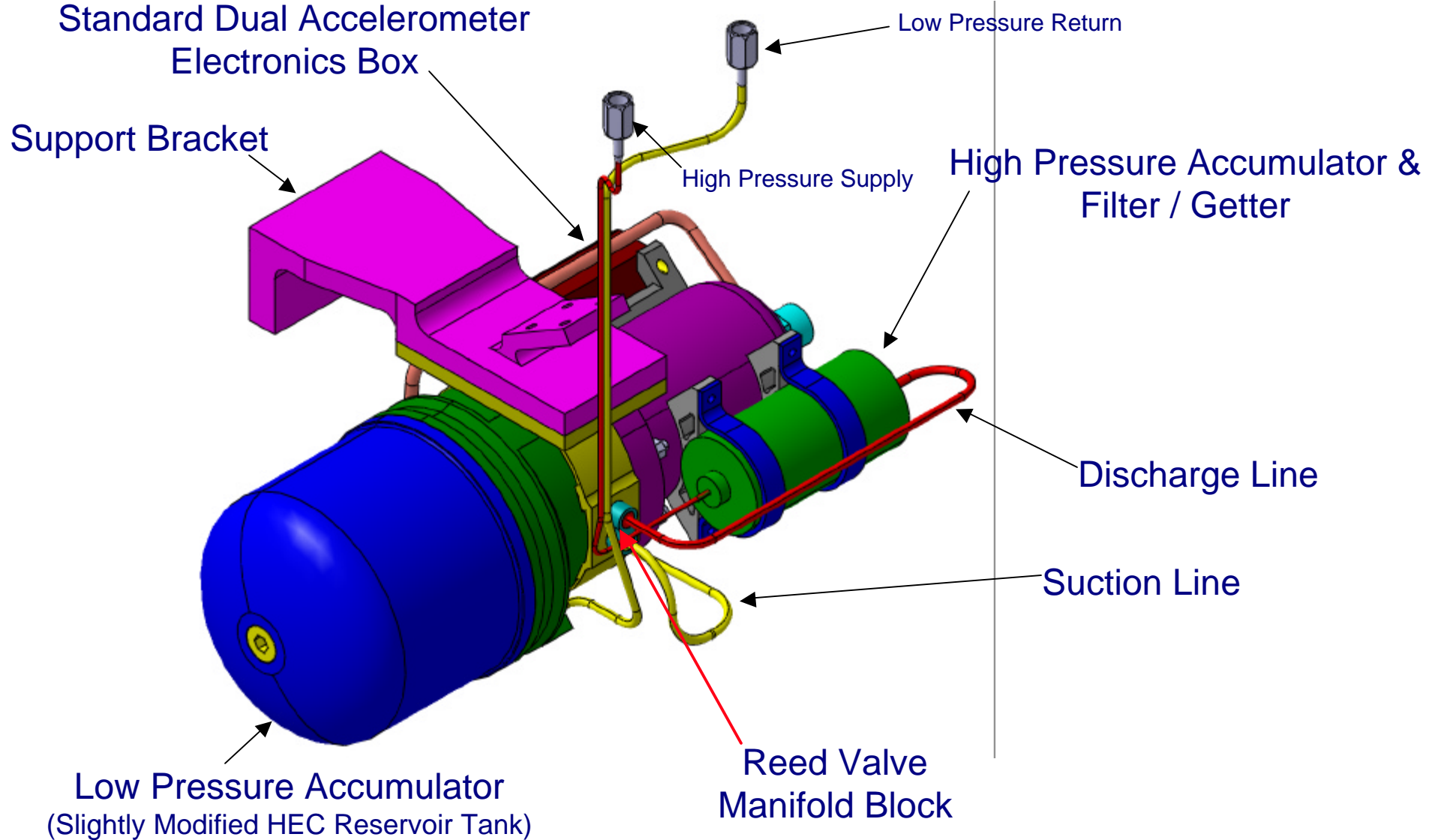
# S/C Bus Mount Assembly – Envelope



# S/C Bus Mount Assembly Components



# JT Compressor Components





# Baseline Electronics Design Description

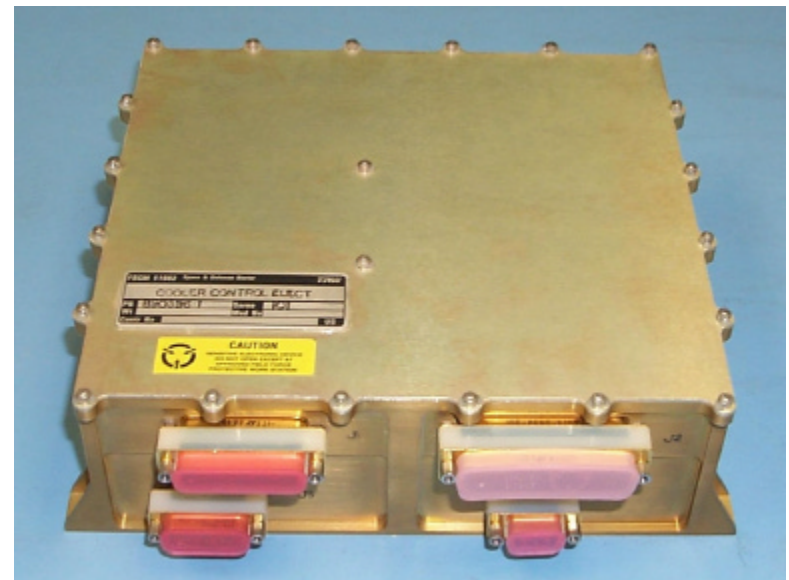
## 3 Electronics boxes:

- One HEC Electronics operates the J-T cooler
- One HEC Electronics operates the pre-cooler
- One Aux Thermometry Electronics provides 8 additional thermometry channels and a fine heater controller for the J-T coldhead

## HEC Development Status (AFRL 95K Program):

- Cryocooler Electronics development complete
- EM unit acceptance tested and ready for delivery
- First flight units to be built on the Hybrid Test Program

**HEC Electronics**

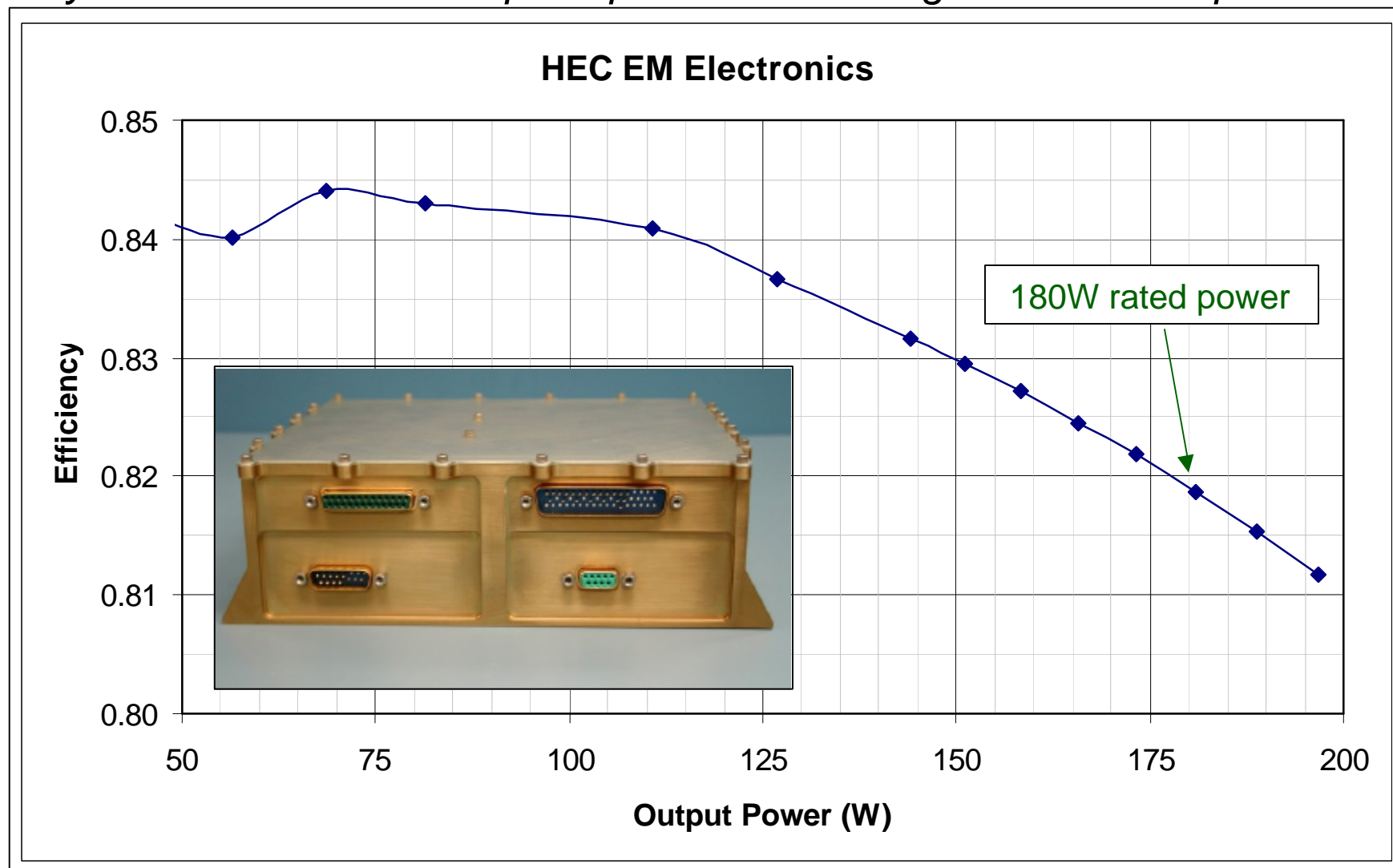


9.20?7.85?2.91  
3.0Kg



# HEC Electronics Efficiency

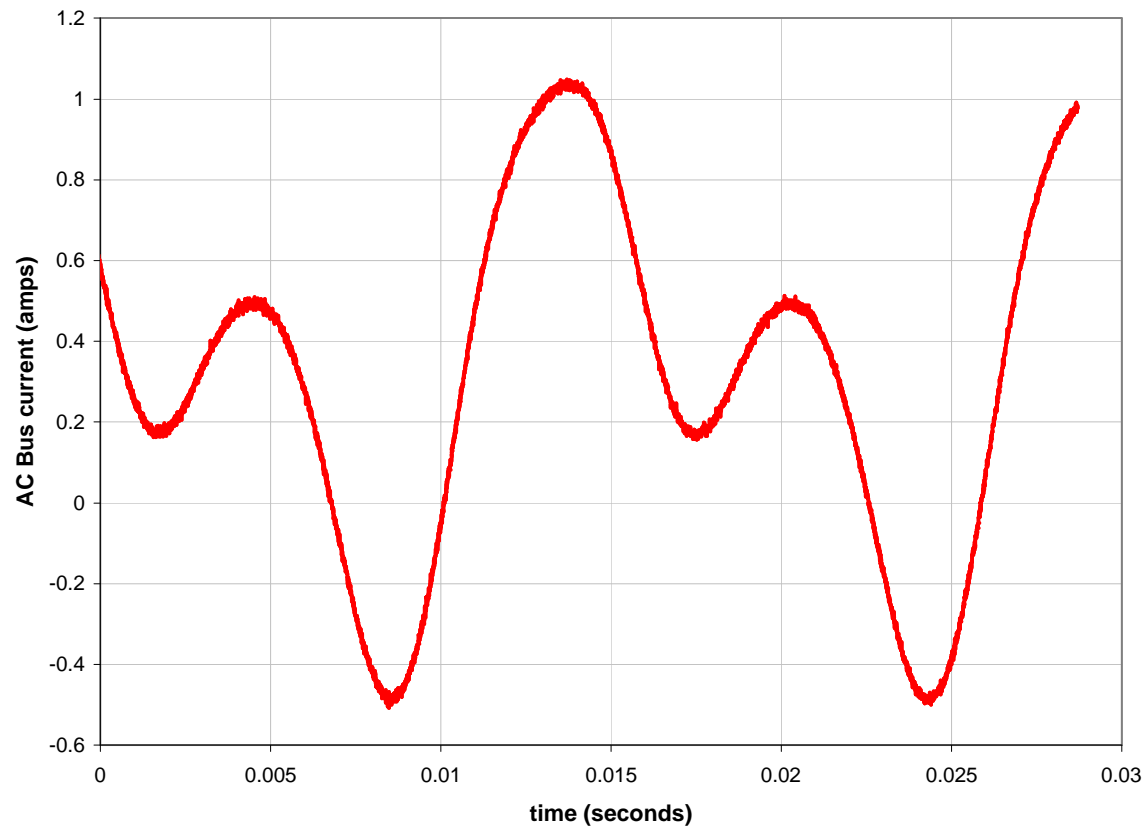
*Very efficient over the complete performance range of delivered power*



## Active Ripple Control Provides >20dB Attenuation

*Active ripple control relieves need for additional ~ 3Kg power bus filter*

HEC Bus Current @ 238 Watts input  
03/18/2003



*Improved power converter under development reduces ripple by another 12dB*

## Summary

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- Program is progressing well
- Long lead hardware (build to print) in fabrication
- Key technical issues are being addressed